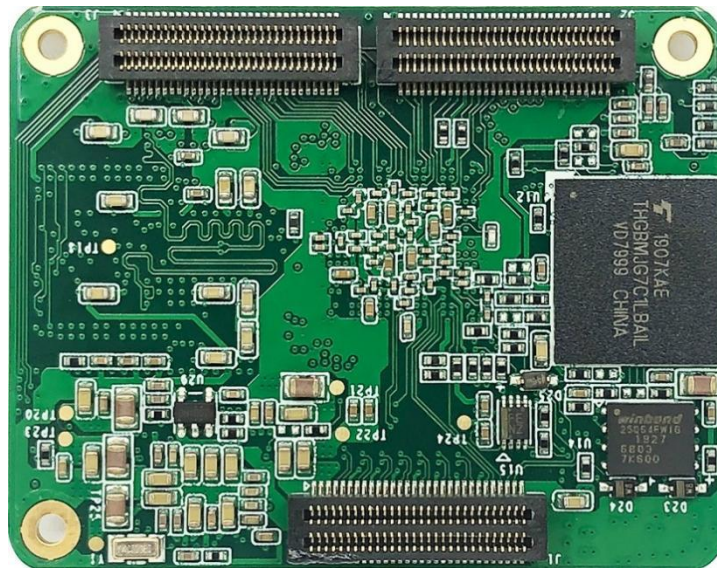
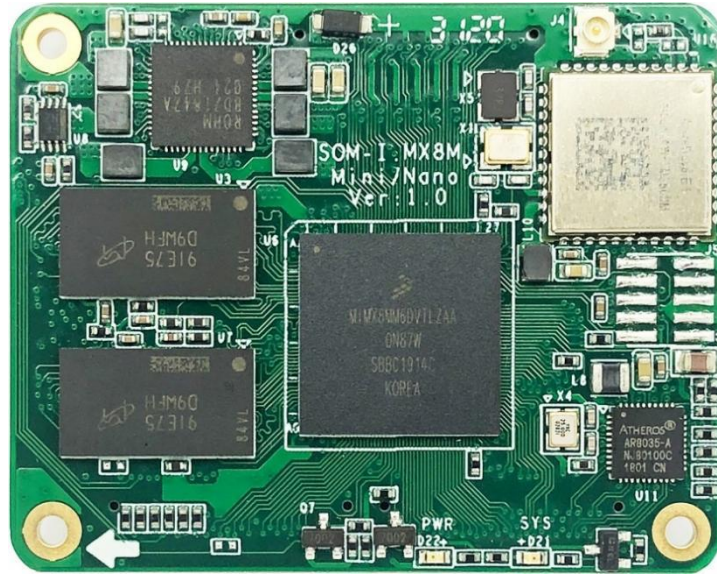


# SOM-IMX8MM Hardware User Manual



## Revision History

Date	Version	Description
2023/6/27	V1.0	Update Github Link
2023/07/14	V1.1	Check Errors

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## 1. General

This document describes the hardware architecture of the SOM-IMX8M-MINI Module.

The SOM-IMX8M-MINI System-On-Module (SOM) board is based on NXP's energy efficient i.MX 8M Mini series processor. For i.MX 8M Mini series processors which has up to 4 x Cortex-A53 cores capable at running up to 1.8 GHz and one Cortex-M4 core capable at running up to 400 MHz core for low-power and real-time operation.

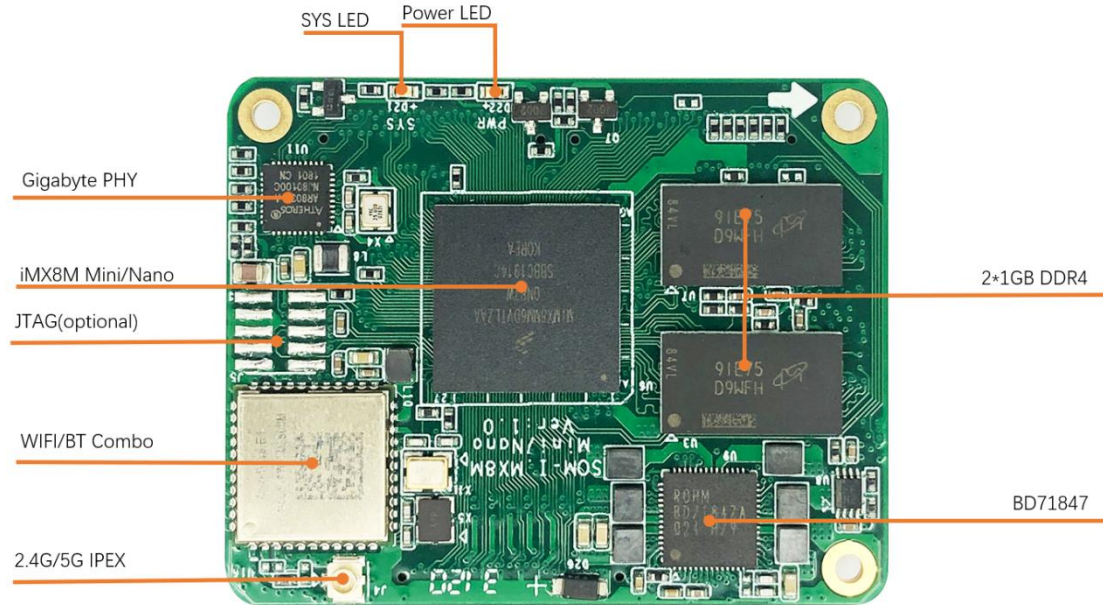
On-board up to 2GB DDR4, up to 64GB eMMC and a WiFi / Bluetooth module, and with MIPI DSI display driver, MIPI CSI camera receiver, flexible audio interfaces and comprehensive communication features. The SOM-IMX8M-MINI Module is a fully-integrated system that helps you build your professional embedded systems rapidly.

Support Linux kernel, Yocto Project file-system, Debian and Android run on the Cortex-A core, and Real-time OS such as UCOS and FreeRTOS run on the Cortex-M core.

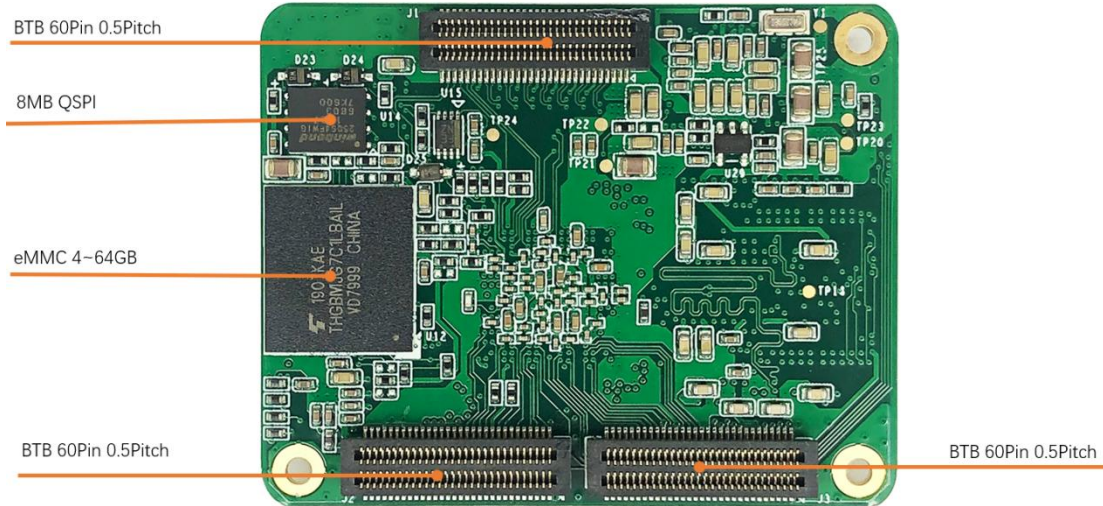
Comes with detailed user manual, ready-made system, and friendly technology support. We are able to provide customize based on this SOM module for various application.

## 2. Features

### 2.1 SOM-IMX8M-MINI



Picture2.1 Top side of SOM-IMX8M-MINI

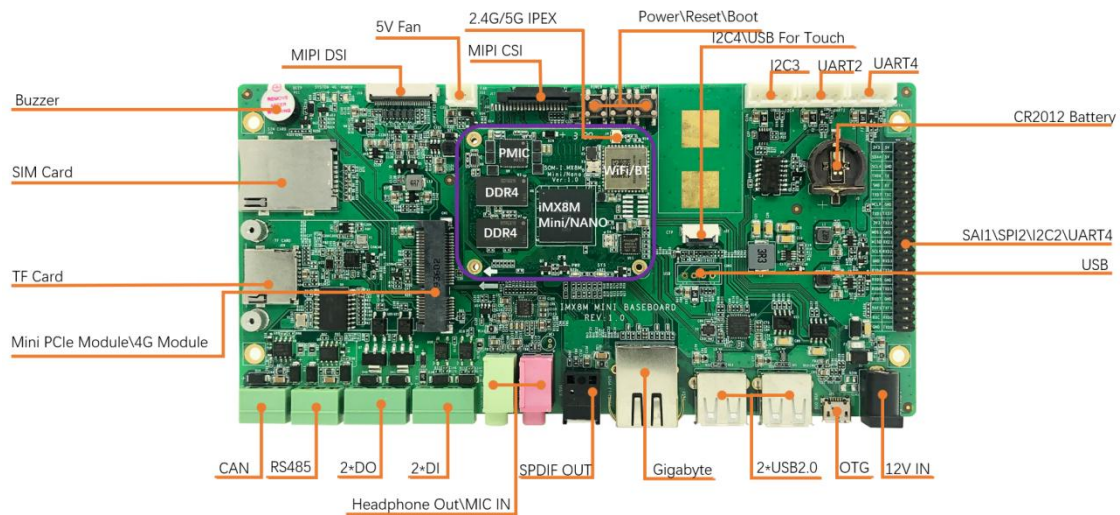


Picture2.2 Bottom side of SOM-IMX8M-MINI

- Up to Quad-core ARM Cortex-A53
- 64-bit Armv8-A architecture
- Target frequency up to 1.8GHz
- 2D/3D GC520L

- Media Processing Engine (MPE) with NEON technology
- Floating Point Unit (FPU) with support of the VFPv4-D16 architecture
- One Cortex-M4 up to 400MHz
- Wi-Fi 1x1 (802.11b/g/n/ac 2.4/5GHz)
- Bluetooth 5.0
- From 8 to 64GB eMMC
- Up to 2GB DDR4
- 64M bit Quad SPI Flash on-board
- 3\*60Pin 0.5mm pitch BTB connectors
- Up to 75xGPIO (including SPI,I2C,PWM,UART,SAI, and SDIO)

## 2.2 DEV-IMX8M-MINI



Picture2.3 DEV-IMX8M-MINI

- 12V Power IN x 1
- USB 2.0 Host x 2
- USB OTG x 1
- USB 2.0 Host (4 Pin Connector) x 1
- UART:

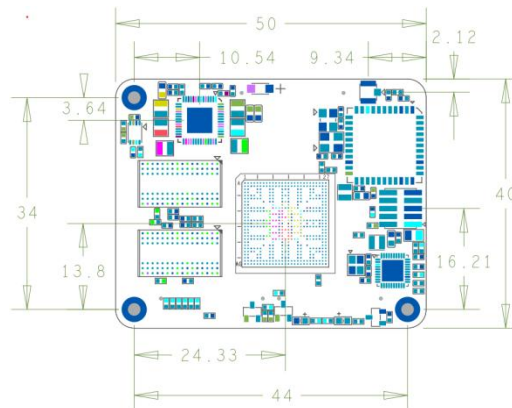
- UART2 (TTL, For Debug)
- UART3 (TTL, For User)
- UART4 (TTL, For User)
  
- I2C x 3
- USB Touch x 1
- MIPI-CSI x 1
- Fan 5V port x 1
- MIPI-DSI x 1
- Buzzer x 1
- SIM Card x 1
- TF Card x 1
- Mini PCIE Interface x 1, For 4G module and PCIE module
- CAN Bus x 1
- RS485 Bus x 1
- Input Terminal x 2 PIN (With Isolation)
- Output Terminal x 2 PIN (With Isolation)
- Headphone Output/MIC In x 1
- SPDIF Out x 1
- 1x Gigabit Ethernet on-board

### 3. Application

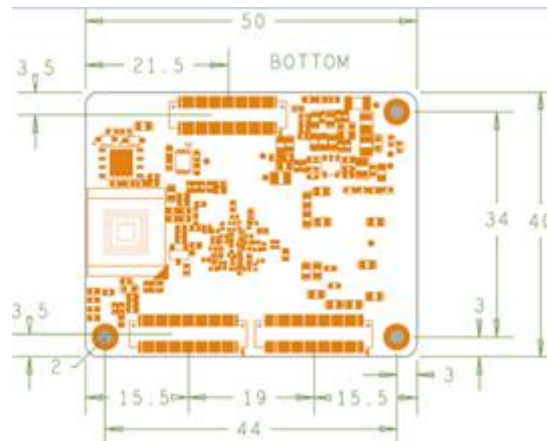
- HMI
- Medical appliances
- Industrial automation
- Weighing Scales
- Smart Toll Systems
- Educational Consoles

## 4. Mechanical Dimension

- Size: 50 x 40 x 7.3 mm
- PCB Parameter: 8 layer design, lead-free soldering process
- Weight: 12g



Picture4.1 Mechanical Dimension of Top side



Picture4.2 Mechanical Dimension of Bottom side



## 5. Electrical Characteristics

### 5.1 Working Temperature

Table5.1 Working Temperature

Specification	Minimum Operating Temperature (°C)	Operating Temperature (°C)
Commercial Grade	0	70
Industrial Grade	−40	+85

Note:

A heat sink may need for some applications

## 6. Hardware Overview

### 6.1 System Components

Table6.1 Hardware Overview

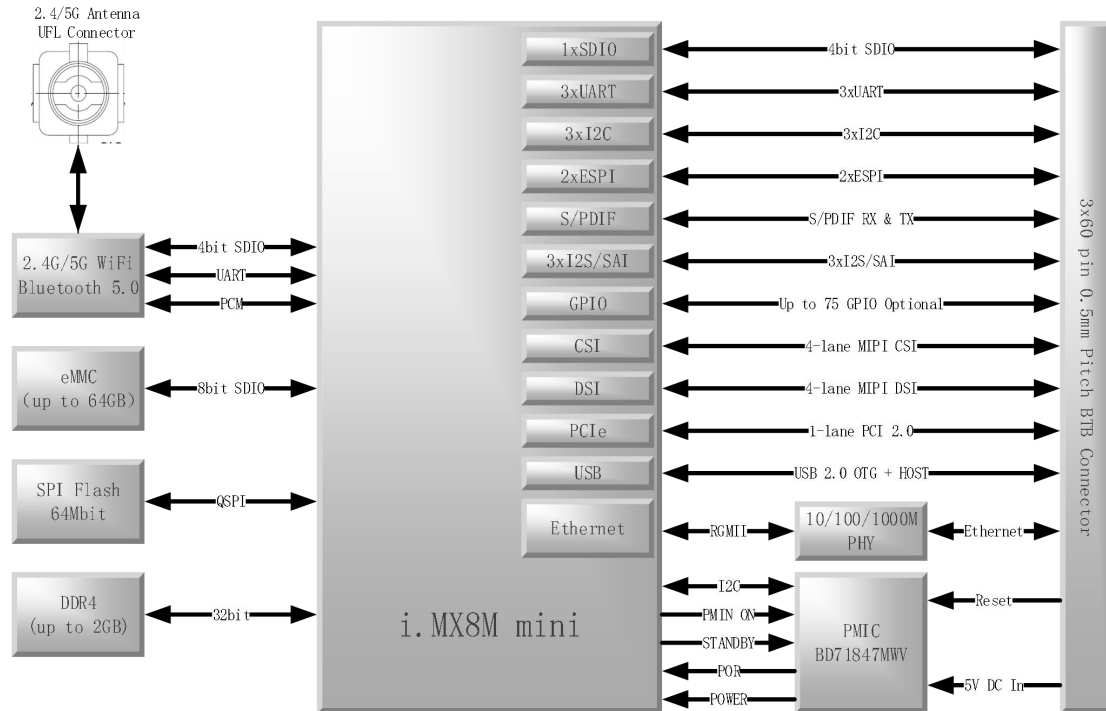
Feature	Details
<b>i.MX8M MINI SOC</b>	
Arm Cortex-A53 MPCore platform	Quad symmetric Cortex-A53 processors, including: <ul style="list-style-type: none"> <li>• 32 KB L1 Instruction Cache</li> <li>• 32 KB L1 Data Cache</li> <li>• Media Processing Engine (MPE)</li> <li>• Floating Point Unit (FPU)</li> </ul> Support of 64-bit Armv8-A architecture <ul style="list-style-type: none"> <li>• 512 KB unified L2 cache</li> <li>• Target frequency of 1.8GHz</li> </ul>
Arm Cortex-M4 core platform	<ul style="list-style-type: none"> <li>• 16 KB L1 Instruction Cache</li> <li>• 16 KB L1 Data Cache</li> <li>• 256 KB TCM</li> </ul>
Graphic Processing Unit (GPU)	<ul style="list-style-type: none"> <li>• GC NanoUltra frequency up to 800 MHz</li> <li>• OpenGL ES 2.0</li> <li>• 2D GC520L</li> </ul>
Video Processing Unit (VPU)	<ul style="list-style-type: none"> <li>• VP9,VP8,AVC,H.265,H.264 decoder</li> <li>• VP8, AVC,H.264 encoder</li> </ul>

Audio	<ul style="list-style-type: none"> <li>• S/PDIF Input and Output</li> <li>• SAI modules supporting I2S,AC97,TDM</li> </ul>
On-chip memory	<ul style="list-style-type: none"> <li>• Boot ROM (256KB)</li> <li>• On-chip RAM (256KB + 32KB)</li> </ul>
<b>Memory and storage</b>	
DDR SDRAM	<ul style="list-style-type: none"> <li>• 2GB DDR4 SDRAM (32-bit bus width)</li> <li>• 1200MHz maximum DDR clock</li> <li>• Interfaces directly to the iMX8M MIPI build-in DDR controller</li> </ul>
eMMC	<ul style="list-style-type: none"> <li>• 8GB NAND eMMC flash memory</li> <li>• 8-bits MMC mode</li> <li>• Conforms to JEDEC version 5.0 and 5.1</li> </ul>
SPI Flash	<ul style="list-style-type: none"> <li>• 64M bit SPI flash memory</li> <li>• 104MHz Single, Dual/Quad SPI clocks</li> <li>• More than 100,000 erase/program cycles</li> <li>• More than 20-year data retention</li> </ul>
Expandable flash (MicroSD)	<ul style="list-style-type: none"> <li>• Meets SD/SDIO 3.0 standard Runs at 4-bits</li> <li>• Supports system boot from SD card</li> </ul>
<b>Network &amp; Wireless</b>	
Ethernet	<ul style="list-style-type: none"> <li>• On-board 10/100/1000 Mbps Ethernet PHY</li> </ul>
Wi-Fi	<p>AzureWave AW-CM256SM module:</p> <ul style="list-style-type: none"> <li>• Wi-Fi 1x1 (802.11a/b/g/n/ac 2.4/5GHz)</li> <li>• SDIO 3.0</li> <li>• High speed wireless connection up to 433.3Mbps</li> </ul>
Bluetooth	<p>AzureWave AW-CM256SM module:</p> <ul style="list-style-type: none"> <li>• Bluetooth 5.0 (supports Bluetooth low-energy)</li> <li>• High-speed UART</li> <li>• PCM audio</li> </ul>
<b>Hardware Interface</b>	
I/O connectivity	<ul style="list-style-type: none"> <li>• 1x single lane PCI Express Gen 2</li> <li>• 2x USB2.0 OTG with integrated PHY</li> <li>• 1x SDIO supporting MMC 5.1, SDIO 3.01</li> <li>• 1x Gigabit Ethernet with integrated PHY</li> <li>• 3x UART</li> <li>• 3x I2C</li> <li>• 2x ESPI</li> </ul>

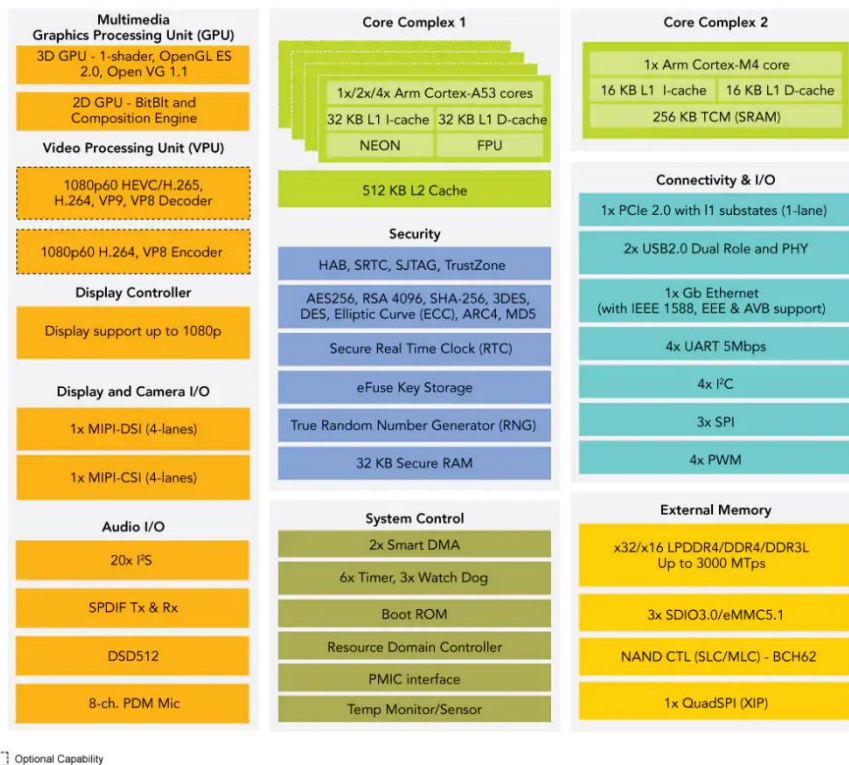
Display Interfaces	• 4-lane MIPI DSI interface
Camera	• 4-lane MIPI CSI interface

## 6.2 Functional Block Diagrams

The following figure is a functional block diagram of the SOM-IMX8M-MINI:



Picture6.1 Functional Block Diagrams

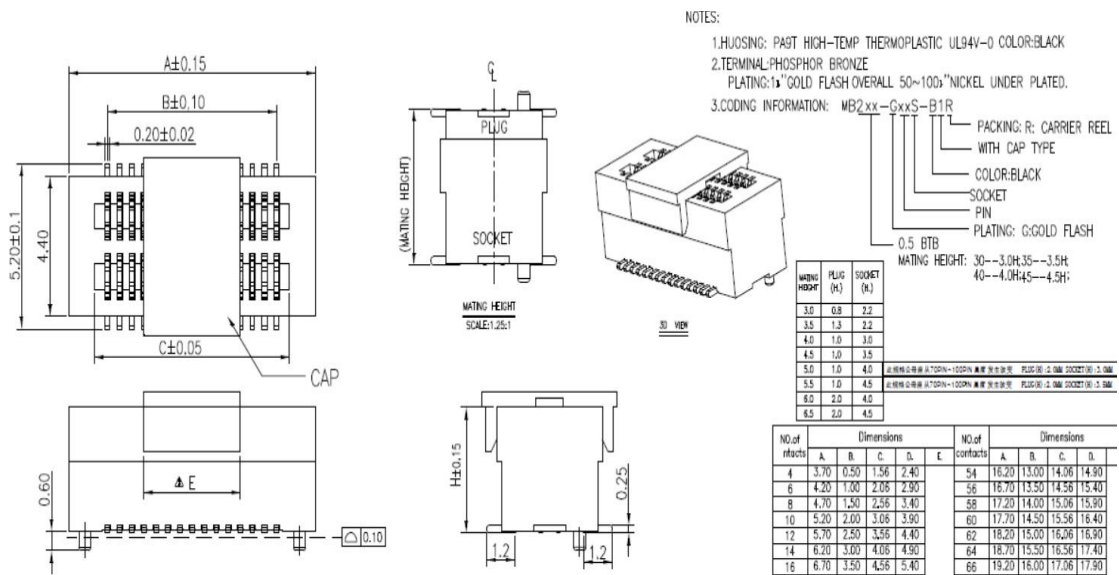


Picture6.2 i.MX 8M Mini system block diagram

## 7. Interface Description

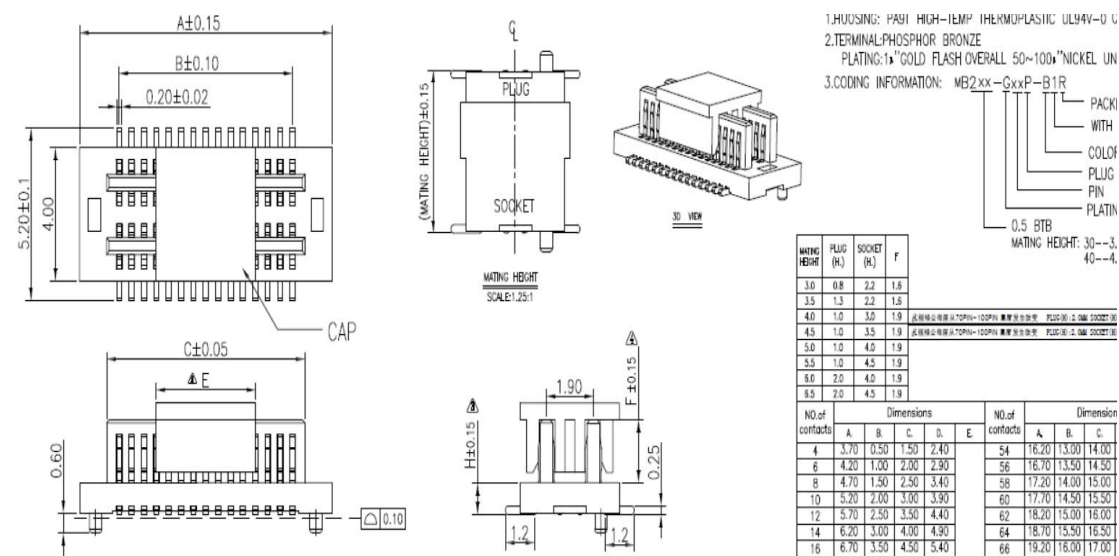
### 7.1 BTB ON Connector

The BTB connector mounted on SOM is MB250-G60S-B1R supplied by MTCNN. The specification of the connector is:



Picture7.1 Connector Specifications For SOM

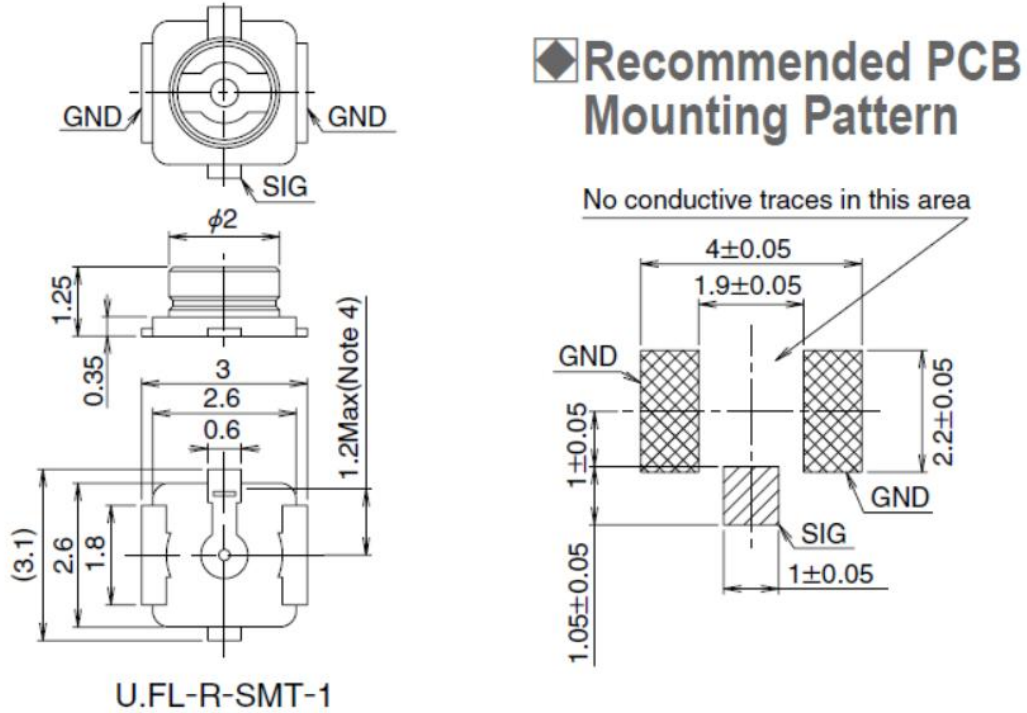
The recommended BTB connector can be mounted on baseboard is MB250-G60P-B1R supplied by MTCNN, an equal parameters BTB connector can be used instead. The specification of the connector is as following:



Picture7.2 Connector Specifications for Baseboard

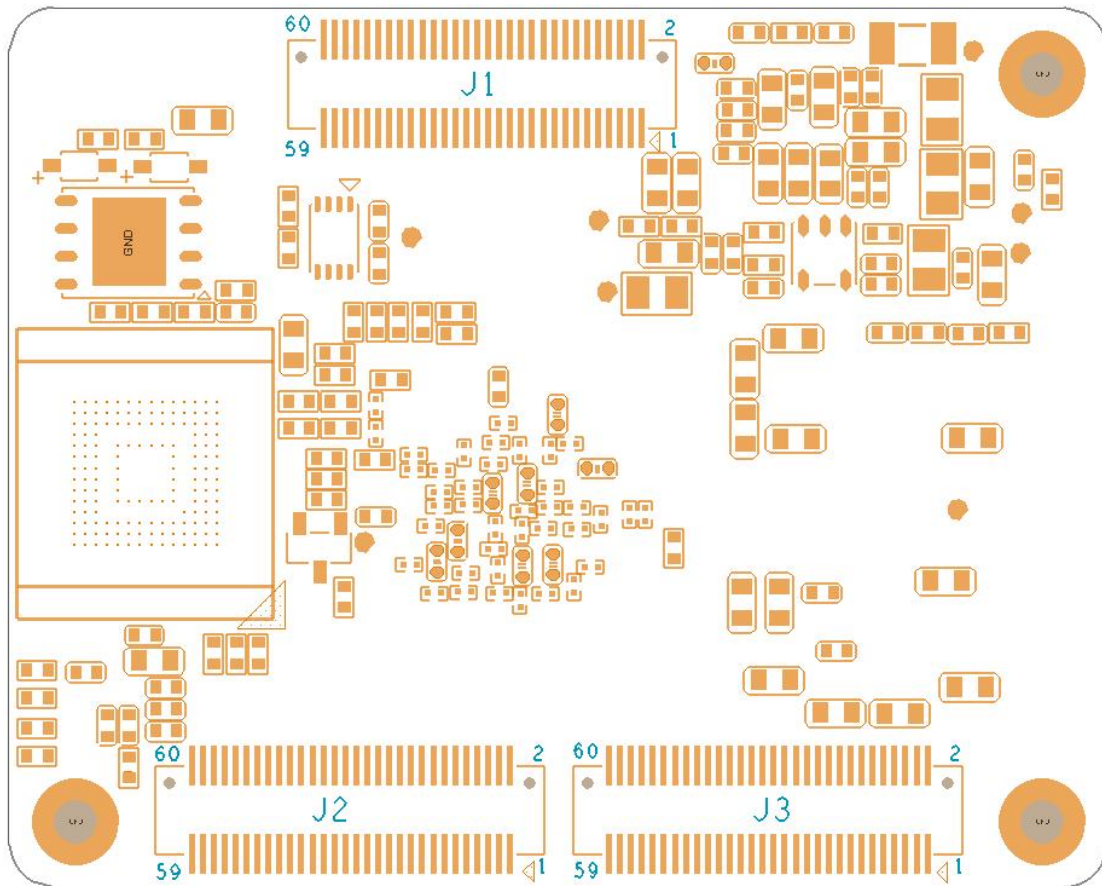
**7.2 WiFi/BT Antenna Connector**

The antenna connector mounted on SOM is Ultra Small Surface Mount Coaxial Connector, the detail of the connector is as following:



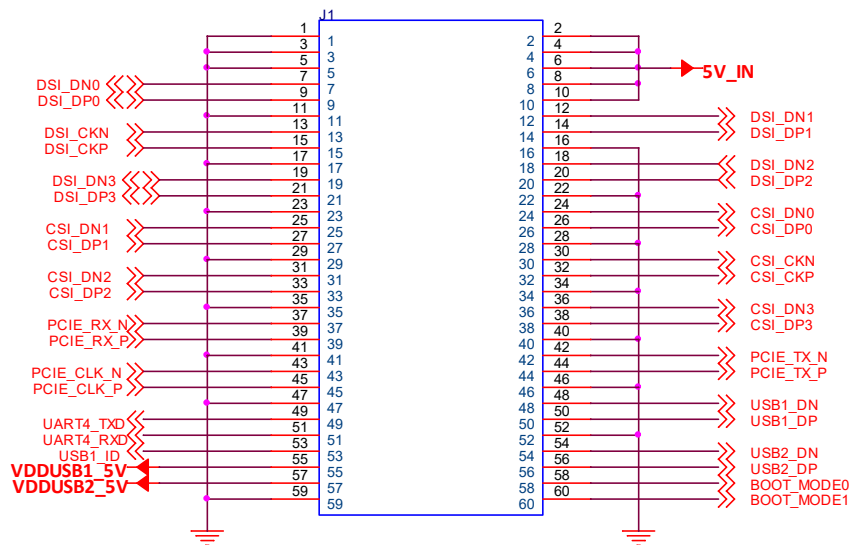
Picture7.3 Specifications For UFL

## 8. Pinout Description Table



Picture8.1 Assemble BTB on bottom side of SOM-IMX8M-MINI





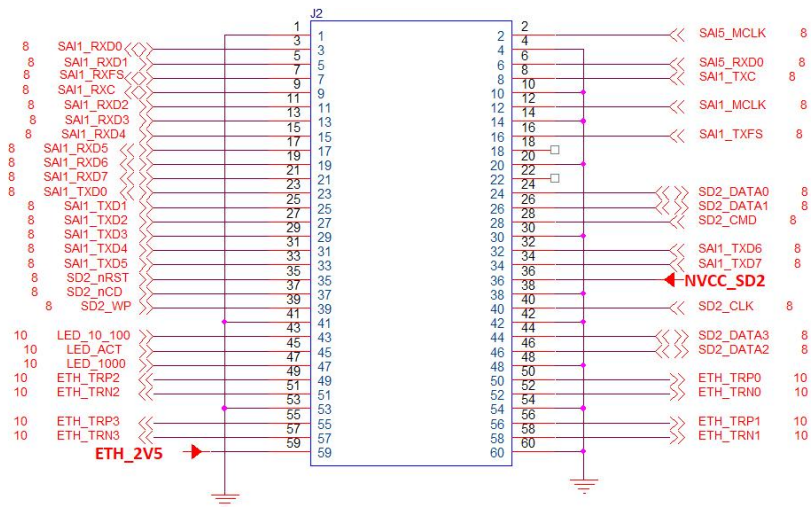
Picture8.2 Pin out of J1

Table8.1 Pin Definition of J1

J1				
Number	Signal	Power Logic	Input/Output	Note
1	GND			
2	5V_IN		Power In	
3	GND			
4	5V_IN		Power In	
5	GND			
6	5V_IN		Power In	
7	DSI_DN0	MIPI DSI		
8	5V_IN		Power In	
9	DSI_DP0	MIPI DSI		
10	5V_IN		Power In	
11	GND			
12	DSI_DN1	MIPI DSI	Output	
13	DSI_CKN	MIPI DSI	Output	
14	DSI_DP1	MIPI DSI	Output	
15	DSI_CKP	MIPI DSI	Output	
16	GND			
17	GND			
18	DSI_DN2	MIPI DSI	Output	
19	DSI_DN3	MIPI DSI	Output	
20	DSI_DP2	MIPI DSI	Output	
21	DSI_DP3	MIPI DSI	Output	
22	GND			

J1				
Number	Signal	Power Logic	Input/Output	Note
23	GND			
24	CSI_DN0	MIPI CSI	Input	
25	CSI_DN1	MIPI CSI	Input	
26	CSI_DP0	MIPI CSI	Input	
27	CSI_DP1	MIPI CSI	Input	
28	GND			
29	GND			
30	CSI_CKN	MIPI CSI	Input	
31	CSI_DN2	MIPI CSI	Input	
32	CSI_CKP	MIPI CSI	Input	
33	CSI_DP2	MIPI CSI	Input	
34	GND			
35	GND			
36	CSI_DN3	MIPI CSI	Input	
37	PCIE_RX_N	PCIe	Input	
38	CSI_DP3	MIPI CSI	Input	
39	PCIE_RX_P	PCIe	Input	
40	GND			
41	GND			
42	PCIE_TX_N	PCIe	Output	
43	PCIE_CLK_N	PCIe	Input	
44	PCIE_TX_P	PCIe	Output	
45	PCIE_CLK_P	PCIe	Input	
46	GND			
47	GND			
48	USB1_DN	USB	In/Out	
49	UART4_TXD	3.3V	In/Out	M4 Debug UART
50	USB1_DP	USB	In/Out	
51	UART4_RXD	3.3V	In/Out	M4 Debug UART
52	GND			
53	USB1_ID	1.8V	Input	Connected to GND or Unconnected
54	USB2_DN	USB	In/Out	
55	USB1_VBUS	USB	Power Detect	Connect USB 5V
56	USB2_DP	USB	In/Out	
57	USB2_VBUS	USB	Power Detect	Connect USB 5V
58	BOOT_MODE0	3.3V	Input	
59	GND			

<b>J1</b>				
<b>Number</b>	<b>Signal</b>	<b>Power Logic</b>	<b>Input/Output</b>	<b>Note</b>
60	BOOT_MODE1	3.3V	Input	10K pull-up 3.3V

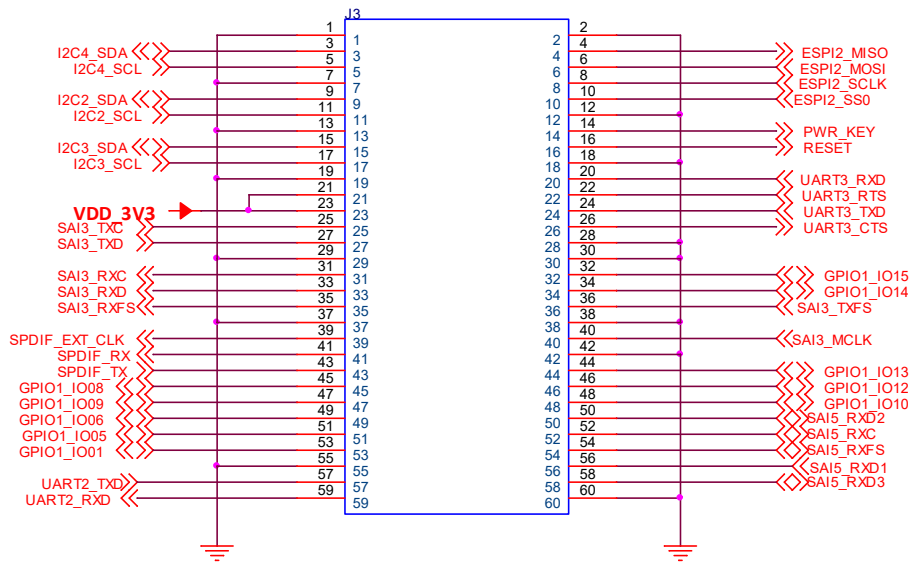


Picture8.3 Pin out of J2

Table8.2 Pin Definition of J2

J2				
Number	Signal	Power Logic	Input/Output	Note
1	GND			
2	SAI5_MCLK	3.3V	In/Out	
3	SAI1_RXD0	3.3V	In/Out	Boot CFG 0
4	GND			
5	SAI1_RXD1	3.3V	In/Out	Boot CFG 1
6	SAI5_RXD0	3.3V	In/Out	
7	SAI1_RXFS	3.3V	In/Out	
8	SAI1_TXC	3.3V	In/Out	
9	SAI1_RXC	3.3V	In/Out	
10	GND			
11	SAI1_RXD2	3.3V	In/Out	Boot CFG 2
12	SAI1_MCLK	3.3V	In/Out	
13	SAI1_RXD3	3.3V	In/Out	Boot CFG 3
14	GND			
15	SAI1_RXD4	3.3V	In/Out	Boot CFG 4
16	SAI1_TXFS	3.3V	In/Out	
17	SAI1_RXD5	3.3V	In/Out	Boot CFG 5
18	NC			No connection
19	SAI1_RXD6	3.3V	In/Out	Boot CFG 6
20	GND			No Connection
21	SAI1_RXD7	3.3V	In/Out	Boot CFG 7
22	NC			
23	SAI1_TXD0	3.3V	In/Out	Boot CFG 8

J2				
Number	Signal	Power Logic	Input/Output	Note
24	SD2_DATA0	NVCC_SD2	In/Out	
25	SAI1_TXD1	3.3V	In/Out	Boot CFG 9
26	SD2_DATA1	NVCC_SD2	In/Out	
27	SAI1_TXD2	3.3V	In/Out	Boot CFG 10
28	SD2_CMD	NVCC_SD2	In/Out	
29	SAI1_TXD3	3.3V	In/Out	Boot CFG 11
30	GND			
31	SAI1_TXD4	3.3V	In/Out	Boot CFG 12
32	SAI1_TXD6	3.3V	In/Out	Boot CFG 14
33	SAI1_TXD5	3.3V	In/Out	Boot CFG 13
34	SAI1_TXD7	3.3V	In/Out	Boot CFG 15
35	SD2_RESET_B	NVCC_SD2	In/Out	
36	NVCC_SD2		Power output	
37	SD2_CD_B	NVCC_SD2	In/Out	
38	GND			
39	SD2_WP	NVCC_SD2	In/Out	
40	SD2_CLK	NVCC_SD2	In/Out	
41	GND			
42	GND			
43	LED_10_100	ETH_2V5	In/Out	AR8035
44	SD2_DATA3	NVCC_SD2	In/Out	
45	LED_ACT	ETH_2V5	In/Out	AR8035
46	SD2_DATA2	NVCC_SD2	In/Out	
47	LED_1000	ETH_2V5	In/Out	AR8035
48	GND			
49	ETH_TRP2	Analog	In/Out	AR8035
50	ETH_TRP0	Analog	In/Out	AR8035
51	ETH_TRN2	Analog	In/Out	AR8035
52	ETH_TRN0	Analog	In/Out	AR8035
53	GND			
54	GND			
55	ETH_TRP3	Analog	In/Out	AR8035
56	ETH_TRP1	Analog	In/Out	AR8035
57	ETH_TRN3	Analog	In/Out	AR8035
58	ETH_TRN1	Analog	In/Out	AR8035
59	ETH_2V5		Power output	Just for Ethernet LED
60	GND			



Picture8.4 Pin out of J3

Table8.3 Pin Definition of J3

J3				
Number	Signal	Power Logic	Input/Output	Note
1	GND			
2	GND			
3	I2C4_SDA	3.3V	In/Out	4.7K pull-up 3.3V
4	ESPI2_MISO	3.3V	In/Out	
5	I2C4_SCL	3.3V	In/Out	4.7K pull-up 3.3V
6	ESPI2_MOSI	3.3V	In/Out	
7	GND			
8	ESPI2_SCLK	3.3V	In/Out	
9	I2C2_SDA	3.3V	In/Out	4.7K pull-up 3.3V
10	ESPI2_SS0	3.3V	In/Out	
11	I2C2_SCL	3.3V	In/Out	4.7K pull-up 3.3V
12	GND			
13	GND			
14	PWR_KEY		Input	100K pull-up 1.8V
15	I2C3_SDA	3.3V	In/Out	4.7K pull-up 3.3V
16	RESET		Input	BD71847MWV
17	I2C3_SCL	3.3V	In/Out	4.7K pull-up 3.3V
18	GND			
19	GND			
20	UART3_RXD	3.3V	In/Out	
21	VDD_3V3		Power output	
22	UART3_RTS	3.3V	In/Out	

J3				
Number	Signal	Power Logic	Input/Output	Note
23	VDD_3V3		Power output	
24	UART3_TXD	3.3V	In/Out	
25	SAI3_TXC	3.3V	In/Out	
26	UART3_CTS	3.3V	In/Out	
27	SAI3_TXD	3.3V	In/Out	
28	GND			
29	GND			
30	GND			
31	SAI3_RXC	3.3V	In/Out	
32	GPIO1_IO15	3.3V	In/Out	
33	SAI3_RXD	3.3V	In/Out	
34	GPIO1_IO14	3.3V	In/Out	
35	SAI3_RXFS	3.3V	In/Out	
36	SAI3_TXFS	3.3V	In/Out	
37	GND			
38	GND			
39	SPDIF_EXT_CLK	3.3V	In/Out	
40	SAI3_MCLK	3.3V	In/Out	
41	SPDIF_RX	3.3V	In/Out	
42	GND			
43	SPDIF_TX	3.3V	In/Out	
44	GPIO1_IO13	3.3V	In/Out	
45	GPIO1_IO08	3.3V	In/Out	
46	GPIO1_IO12	3.3V	In/Out	
47	GPIO1_IO09	3.3V	In/Out	
48	GPIO1_IO10	3.3V	In/Out	
49	GPIO1_IO06	3.3V	In/Out	
50	SAI5_RXD2	3.3V	In/Out	
51	GPIO1_IO05	3.3V	In/Out	
52	SAI5_RXC	3.3V	In/Out	
53	GPIO1_IO01	3.3V	In/Out	
54	SAI5_RXFS	3.3V	In/Out	
55	GND			
56	SAI5_RXD1	3.3V	In/Out	
57	UART2_TXD	3.3V	In/Out	A53 Debug UART
58	SAI5_RXD3	3.3V	In/Out	
59	UART2_RXD	3.3V	In/Out	A53 Debug UART
60	GND			

Official Website: <a href="http://www.emtop-tech.com">www.emtop-tech.com</a>	Wiki Page: <a href="https://github.com/EMTOP-TECH">https://github.com/EMTOP-TECH</a>
Sales Contact: <a href="mailto:sales@emtop-tech.com">sales@emtop-tech.com</a>	Support Contact: <a href="mailto:support@emtop-tech.com">support@emtop-tech.com</a>



## 9. Power Supply And System Resets

### 9.1 Power Source

The SOM-IMX8M-MINI have built-in power management function, so it is only need to provide a +5V power source to the SOM-IMX8M-MINI via the 5V input pins of the J1 connector.

The power consumption is requested **2A/5V(10 W)** at least for the IMX8M-MINI-SOM board to be working properly.

### 9.2 Power Control and Monitoring

Power control and monitoring on the IMX8M-IMX8M-MINI is implemented using the ROHM Power Control Integrated Circuit (PMIC) BD71847MWV-E2, designed specifically for the NXP i.MX8M MINI family of application processors.

The BD71847MWV-E2 provides Dynamic Voltage Scaling via I<sup>2</sup>C bus. The PMIC is accessible on the i.MX8M I2C1 bus for read and write at addresses 0x97 and 0x96, respectively.

### 9.3 System power

The SOM requires 5V as power input (at 5V\_IN). The SOM then generates the power rails for all SOM components through the on-board ICs. Tolerance for power supply is 5V +/- 0.3V.

#### Caution:

- (1) Do not connect the ETH\_2V5/ VDD\_3V3/ NVCC\_SD2 power output pins to any high current devices or you might brownout the system. These power lines are shared with internal SOM circuits, so there is no safe limit for a high current device, but you can safely use them for low current tasks such as for a level shifter or pullup/down.
- (2) Do not connect any of the 3.3V I/O pins to a device that draws more than 82 mA of power or you will brownout the system.
- (3) You must provide a cooling solution to ensure the SOM surface maintains an operational temperature as specified in the environmental reliability section. You can use the SOM's threaded standoffs to mount a passive or active cooling solution.

### 9.4 Power Consumption Typical Values

The following table lists the power draw for certain SOM components during different operational tests.

It is only a reference value, the actual values also relates to the sources of the SOM module you are using.

Table9.1 Power Consumption

Operational Test	SOM Power Values
Sleep	
Idel	

<b>High Performance</b>	
-------------------------	--

## 10. System Resets

### 10.1 Power-on Reset

This type of reset occurs when the power is initially applied to the SOM-IMX8M-MINI. As the supply voltage rises, the on-board PMIC holds the i.MX 8M MINI in reset until all the processor power supply voltages have risen above the appropriate voltage thresholds (90% of the nominal values). The internal power-on reset generation is disabled.

### 10.2 Brown-out Reset

In case any processor supply falls below/rises above its 80%/130% of its nominal voltage level, the PMIC generates a reset for the i.MX 8M MINI. After the brown-out reset has occurred, the PMIC holds the i.MX 8M in reset until all the supplies return to the range 90-110% of their nominal values.

### 10.3 Software Reset

This type of reset is activated by software running on the SOM through performing the i.MX 8M MINI software reset sequence.

### 10.4 External Reset

To activate this type of reset, a baseboard drives low the SYS\_nRST signal on the SOM-IMX8M-Mini interface connectors. Activating this signal leads to the i.MX8M MINI SOM power cycle.

## 11. Boot Mode

Use the BOOT\_MODE[1:0] pins to configure the SOM boot mode setting as indicated in the following tables. The default configure is Internal boot.

Table11.1 Boot Mode

BOOT_MODE1	BOOT_MODE0	Boot type
0	0	Boot from fuses
0	1	Serial downloader
1	0	<b>Internal boot, BOOT_CFG[15:0] are used to enable boot configure.</b>
1	1	Reserved

The boot configuration is specified by the iMX8M MINI SOC, so for more details, refer to the iMX8M MINI SOC documentation.

## 12. Trace impedance recommendations

The following table lists the recommended impedance for high-speed signals on the baseboard.

Table12.1 Trace Impedance Recommendation

Signal group	Impedance	PCB manufacture tolerance
All single-ended signal, unless specified	50 Ohm single-ended	+/-10%
PCIe TX/RX data pair	85 Ohm differential	+/-10%
PCIe differential clocks	100 Ohm differential	+/-10%
USB differential signals	90 Ohm differential	+/-10%
Ethernet Differential signals	100 Ohm differential	+/-10%
MIPI DSI	100 Ohm differential	+/-10%
MIPI CSI	100 Ohm differential	+/-10%

## 13. High-speed signal trace length compensation

The following table lists the trace length of high-speed signals, including MIPI CSI, MIPI DSI, PCIE, USB and Giga Ethernet. Those signals are high-speed signals that require the total etched trace lengths to be equal to each other. Due to space constraints on the SOM, the trace length of those signals currently are not equal. The designer must incorporate the length difference on the baseboard such that the trace length for all high-speed signals match each other.

Table13.1 Trace Length Compensation Of SOM

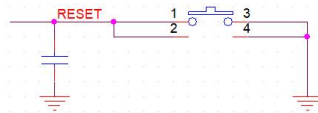
Name	Etch length(mils)	Manhattan length(mils)
<b>MIPI CSI</b>		
CSI_CKN	648.69	602.09
CSI_CKP	652.53	634.84
CSI_DN0	660.12	621.78
CSI_DP0	664.04	621.78
CSI_DN1	499.98	464.3
CSI_DP1	504.4	464.31
CSI_DN2	492.11	444.62
CSI_DP2	490.91	477.36
CSI_DN3	639.01	615.15
CSI_DP3	643.82	654.53
<b>MIPI DSI</b>		
DSI_CKN	515.05	503.66
DSI_CKP	519.04	503.67
DSI_DN0	510.88	523.35
DSI_DP0	515.6	523.35
DSI_DN1	653.06	661.15
DSI_DP1	657.2	661.15

DSI_DN2	665.93	641.46
DSI_DP2	668.04	641.47
DSI_DN3	511.74	483.98
DSI_DP3	516.23	483.98
<b>PCIe</b>		
PCIE_CLK_N	495.48	477.35
PCIE_CLK_P	495.7	516.73
PCIE_RX_N	475.14	457.67
PCIE_RX_P	487.48	497.04
PCIE_TX_N	623.25	634.84
PCIE_TX_P	649.18	674.21
<b>USB1</b>		
USB1_DN	647.78	654.52
USB1_DP	652.37	693.9
<b>USB2</b>		
USB2_DN	676.18	693.89
USB2_DP	680.79	733.26
<b>Ethernet</b>		
ETH_TRN0	246.14	172.62
ETH_TRP0	250.02	208.05
ETH_TRN1	225.73	145.06
ETH_TRP1	225.39	149
ETH_TRN2	373.36	408.84
ETH_TRP2	377.4	412.78
ETH_TRN3	348.17	397.03
ETH_TRP3	350.36	400.97

## 14. Circuit Example

### 14.1 Reset In

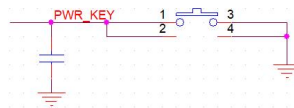
For the reset pin J3.16, a reset button to pull this pin to ground to reset core board is necessary, the ESD component and bypass capacitor is used according to the actual design, a resistor pull up to power supply is installed on SOM board, so not any resistors pull up/down is need.



Picture14.1 Reset In

### 14.2 Power Key

For the power pin J3.14, assert this pin to ground to indicate a power event. Long press to turn off the SOM board and short press to turn on the SOM board. The ESD component and bypass capacitor is used according to the actual design, a resistor pull up to power supply is installed on SOM board, so not any resistors pull up/down is need.



Picture14.2 Power Key

### 14.3 Boot Mode

The power used for pull up resistors for boot configuration should source from SOM board to avoid any unpredictable failure. The power output pins are J3.21 and J3.23.

The following figure shows to boot up from eMMC on SOM board.

Picture14.3 Boot up eMMC on SOM

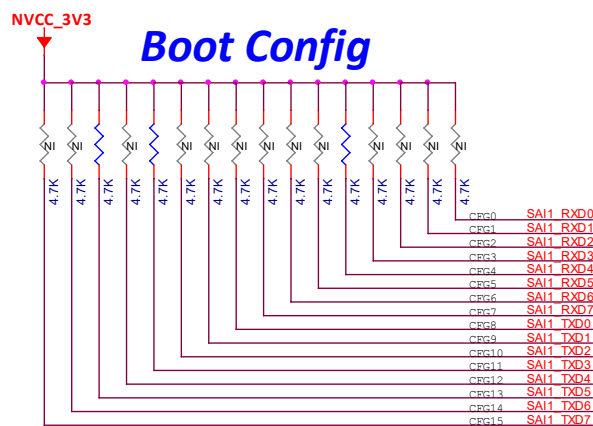
If the designer the board up from storage device, following table to boot-up further information

**i.MX 8M Mini Applications Processor Reference Manual.**

**Caution:** The pull-up resistor of boot configuration should be connected to NVCC\_3V3 from J3.

On-board eMMC: Connected to uSDHC3 8 bit

TF single on BTB connector: Connected to uSDHC2



from the

desires to boot any other please refer the change the configuration, please refer to

On-board QSPI Flash: Connected to QSPI, 1.8V 64M bit QSPI flash, W25Q64FW

*i.MX8M Mini ROM Fuse*

Address		7	6	5	4	3	2	1	0
		BOOT_CFG[15]	BOOT_CFG[14]	BOOT_CFG[13]	BOOT_CFG[12]	BOOT_CFG[11]	BOOT_CFG[10]	BOOT_CFG[9]	BOOT_CFG[8]
	0x470[15:8]	Infinite-Loop (Debug USE only) 0 - Disable 1 - Enable	001 - SD/eSD			Port Select: 00 - uSDHC1 01 - uSDHC2 10 - uSDHC3		Power Cycle Enable '0' - No power cycle '1' - Enabled via	SD Loopback Clock Source Sel (for SDR50 and SDR104 only) '0' - through SD pad '1' - direct
	0x470[15:8]		010 - MMC/eMMC						
	0x470[15:8]		011 - NAND			Pages In Block: 00 - 128 01 - 64 10 - 32 11 - 256		Nand_Row_address_bytes: 00 - 3 01 - 2 10 - 4 11 - 5	
	0x470[15:8]		100 - QSPI			Flash Auto Probe	FLASH_TYPE 000 - Device supports 3B read by default 001 - Device supports 4B read by default 010 - HyperFlash 1V8 011 - HyperFlash 3V3 100 - MMC Octal DDR		
	0x470[15:8]		110 - SPI NOR			Port Select: 000 - eCSPI1 001 - eCSPI2 010 - eCSPI3			SPI Addressing: 0 - 3-bytes (24-bit) 1 - 2-bytes (16-bit)
	0x470[15:8]		Others - Reserved for future use						
		BOOT_CFG[7]	BOOT_CFG[6]	BOOT_CFG[5]	BOOT_CFG[4]	BOOT_CFG[3]	BOOT_CFG[2]	BOOT_CFG[1]	BOOT_CFG[0]
<b>SD/eSD</b>	0x470[7:0]	Fast Boot: 0 - Regular 1 - Fast Boot	Reserved	Reserved	Bus Width: 0 - 1-bit 1 - 4-bit	Speed 000 - Normal/SDR12 001 - High/SDR25 010 - SDR50 011 - SDR104 101 - Reserved for DDR50 Others - Reserved		Reserved	
<b>MMC/eMMC</b>	0x470[7:0]		Bus Width: 000 - 1-bit 001 - 4-bit 010 - 8-bit 101 - 4-bit DDR (MMC 4.4) 110 - 8-bit DDR (MMC 4.4) Else - reserved.			Speed 00 - Normal 01 - High 10 - Reserved for HS200 11 - Reserved		USDHC IO VOLTAGE SELECTION For Normal Boot Mode 0 - 3.3V 1 - 1.8V	USDHC IO VOLTAGE SELECTION For Manufacture Mode 0 - 3.3V 1 - 1.8V
<b>NAND</b>	0x470[7:0]	BT_TOGGLEMODE	BOOT_SEARCH_COUNT: 00 - 2 01 - 2 10 - 4 11 - 8		Toggle Mode 33MHz Preamble Delay, Read Latency: '000' - 16 GPMICLK cycles. '001' - 1 GPMICLK cycles. '010' - 2 GPMICLK cycles. '011' - 3 GPMICLK cycles. '100' - 4 GPMICLK cycles. '101' - 5 GPMICLK cycles. '110' - 6 GPMICLK cycles. '111' - 7 GPMICLK cycles. '1111' - 15 GPMICLK cycles.			Reserved	
<b>FlexSPI</b>	0x470[7:0]	HOLD TIME: 00 - 500us 01 - 1ms 10 - 3ms 11 - 10ms		FLASH Auto Probe Type		FlexSPI FLASH Dummy Cycle			
<b>SPINOR</b>	0x470[7:0]	CS select SPI only: 00 - CS#0 default 01 - CS#1 10 - CS#2 11 - CS#3	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved

Picture14.4 Table For Boot Configure

## 14.4 Giga Ethernet

Use a 0.1uF capacitor as bypass capacitor connect to TCT and RCT of the transformer but do not connect these pins to any power supply.

The 49.9R and capacitor matching networks are not necessary to the differential network. The designer should decide using these resistors and capacitors or not according to their design. For LED\_ACT Pin that is J2.45, parallel LED output for 10/100/1000 BASE-T activity, active blinking. LED active low and is 3.3V tolerated.

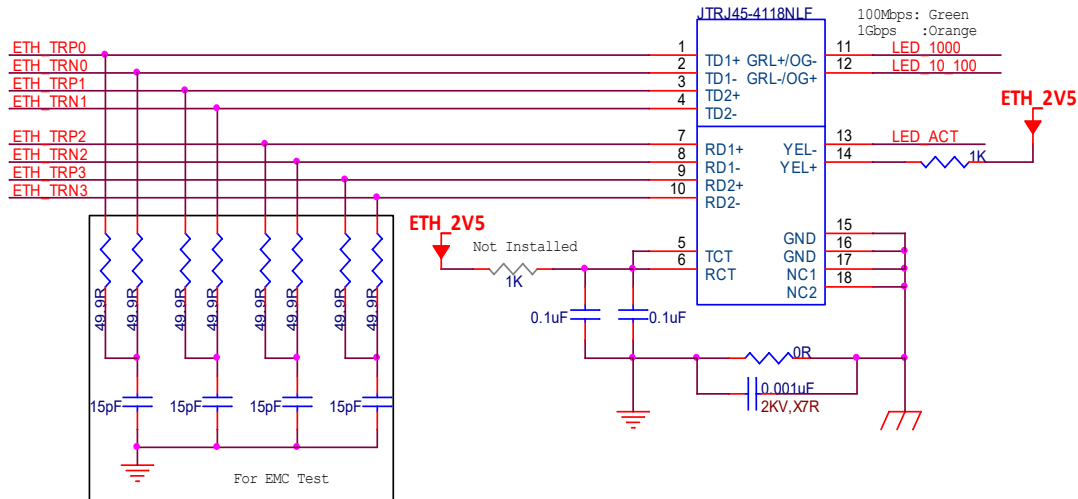
For LED\_1000 Pin that is J2.47, parallel LED output for 1000 BASE-T link, LED active low and is 3.3V tolerated.

For LED\_10\_100 Pin that is J2.43, parallel LED output for 10/100 BASE-T link. LED active low and is 3.3V tolerated.

Symbol	10M Link	10M Active	100M Link	100M Active	1000M Link	1000M Active
LED_10_100	OFF	OFF	ON	ON	OFF	OFF
LED_1000	OFF	OFF	OFF	OFF	ON	ON
LED_ACT	ON	BLINK	ON	BLINK	ON	BLINK

**NOTE:** Notes: on = active; off = inactive

Picture14.5 LED Status

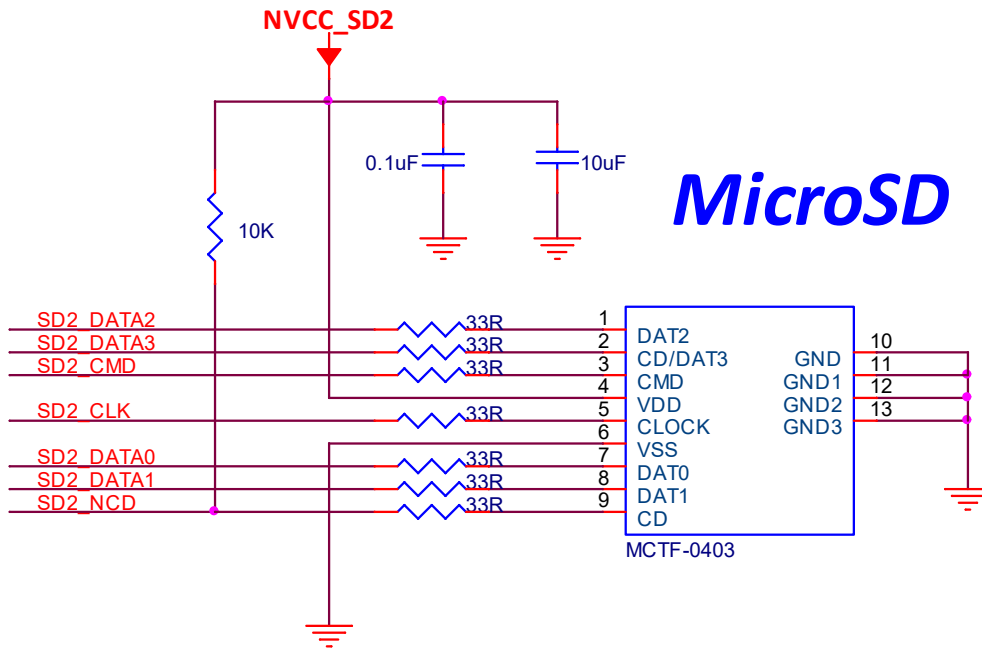


Picture14.6 GBE Demo

## 14.5 TF Card

It is strongly recommended that use the power source NVCC\_SD2 output from J2.36 to power the memory card, and NVCC\_SD2 DO NOT use to power other devices. The voltage level of NVCC\_SD2 can be changed through software to support the high speed mode. Note that maximum current output is 150mA. Do not exceed 150mA at any time to avoid any unpredictable failure.

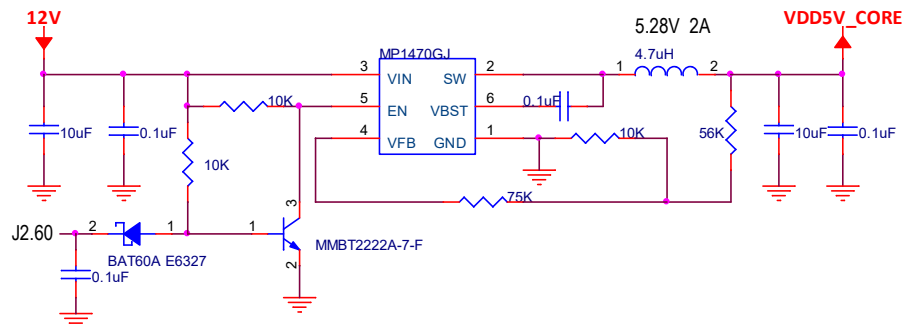




Picture14.7 TF Card Design Demo

### 14.6 SOM Power-Up Enable

Suggest that using J2.60 (GND) on SOM to enable the 5V power supply for SOM as the following demo circuit. There will be no 5V power supply from the BTB connector on Baseboard while no SOM installed, it can protect SOM board from hog plug-in.



Picture14.8 Power supply for SOM-IMX8M-MINI

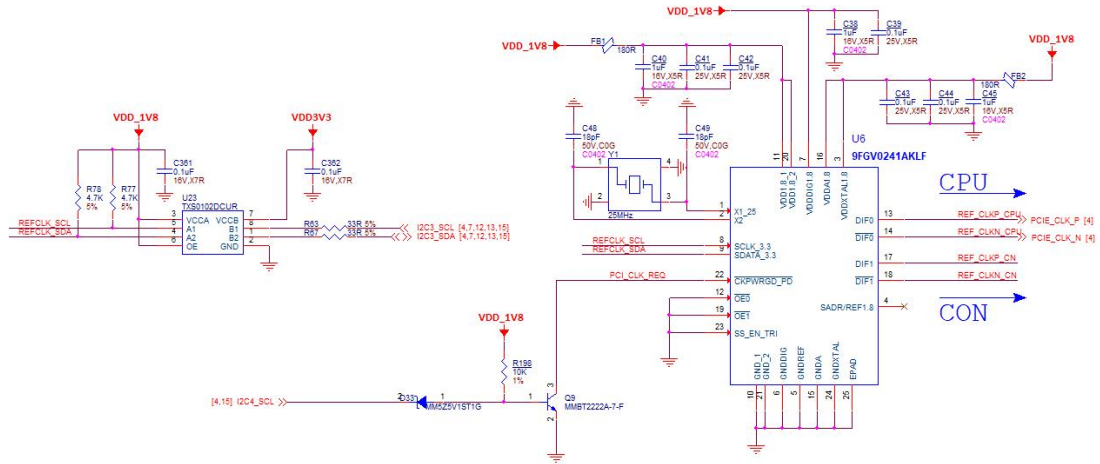
GPIO1\_IO05: During reset: output high without PU/PD; After reset: input with PU  
 SAI5\_CLK: During reset: input without PU/PD; After reset: input with PD

### 14.7 PCIe Clock

In order to boot up the system smoothly, a PCIe differential clock input is necessary. For example, a 100MHz differential clock input to J1.43 and J1.45 on DEV-IMX8M-MINI is design to complete the PCIe function and boot up the system smoothly. If the baseboard does not need the PCIe

function and the designer desire to remove the PCIe reference clock circuit. Please contact the sales for defining firmware.

The PCIe reference clock design for reference as follow.



Picture14.9 PCIe reference clock